



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

In re application of: Cheng et al.

Attorney Docket No.: 01-695/LSI1P184

Application No.: 09/996,118

Examiner: Rao, S.

Filed: November 27, 2001

Group: 2814

Title: Low Resistance Metal Interconnect Lines
and a Process for Fabricating Them

[Handwritten signature]
8/15/04

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Mail Stop After Final, Commissioner for Patents, P.O. Box 1450, Arlington, VA 22313-1450 on November 20, 2003.

Signed: *[Handwritten signature]*

Mia Mitchell-Haynes

Amendment After Final

Mail Stop AF
Commissioner for Patents
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Sir:

Please consider the following amendments and remarks in response to the Final Office Action mailed on October 1, 2003. Amendments to the Claims are reflected in the listing of the claims commencing on page 2. Remarks and arguments begin on page 4 of this paper.

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DEC - 1 2003
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